

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: OGINO , et al.

Serial No.: 10/802,816

Filed: 3/18/2004

Title: MOLD STRUCTURES, AND METHOD OF TRANSFER OF FINE
STRUCTURES

Examiner: Daniels

Conf. No.: 5867

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT
UNDER 37 CFR 1.97 & 1.98

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

April 21, 2010

Sir:

Supplemental to the Information Disclosure Statement filed on February 25, 2009, applicants are submitting herewith a full English translation of the Notice of Rejection for the corresponding Japanese Patent Application No. 2003-078460.

It is respectfully requested that this information disclosure statement be considered by the Examiner.

Please charge any shortage in the fees due in connection with the filing of this paper, including excess claim fees, to Deposit Account No. 01-2135 (1021.43672X00), and please credit any excess fees to such deposit account.

Respectfully submitted,

ANTONELLI, TERRY, STOUT & KRAUS, LLP

/Alan E. Schiavelli/

Alan E. Schiavelli

Registration No. 32,087

AES/at